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Subramanian S. Iyer (Subu) is Distinguished Professor and holds the Charles P. Reames Endowed Chair in the Electrical Engineering Department and a joint appointment in the Materials Science and Engineering Department at the University of California at Los Angeles. He is Director of the Center for Heterogeneous Integration and Performance Scaling (UCLA CHIPS). Prior to that he was an IBM Fellow. His key technical contributions have been the development of the world's first SiGe base HBT, Salicide, electrical fuses, embedded DRAM and 45nm technology node used to make the first generation of truly low power portable devices as well as the first commercial interposer and 3D integrated products. He also was among the first to commercialize bonded SOI for CMOS applications through a start-up called SiBond LLC. More recently, he has been exploring new packaging paradigms and device innovations that may enable wafer-scale architectures, in-memory analog compute and medical engineering applications. He has published over 300 papers and holds over 75 patents. He has received several outstanding technical achievements and corporate awards at IBM. He is an IEEE Fellow, an APS Fellow, an iMAPS Fellow and a Distinguished Lecturer of the IEEE EDS and EPS and a member of the Board of Governors of IEEE EPS. He is also a Fellow of the National Academy of Inventors. He is a Distinguished Alumnus of IIT Bombay and received the IEEE Daniel Noble Medal for emerging technologies in 2012 and the 2020 iMAPS Daniel C. Hughes Jr Memorial award and the iMAPS distinguished educator award in 2021.